

TRANSMITTAL LETTER
(General - Patent Pending)

Docket No.
EN9-98-072US2

In Re Application Of: Enroth et al.

Serial No.

09/777,976

Filing Date

2/6/01

Examiner

Smith, Sean P.

Group Art Unit

3729

Title: WAVE SOLDER APPLICATION FOR BALL GRID ARRAY MODULES

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TO THE ASSISTANT COMMISSIONER FOR PATENTS:

OCT 17 2002

Transmitted herewith is:

TECHNOLOGY CENTER R3700

Amendment

in the above identified application.

- No additional fee is required.
- A check in the amount of _____ is attached.
- The Assistant Commissioner is hereby authorized to charge and credit Deposit Account No. 09-0457(IBM) as described below. A duplicate copy of this sheet is enclosed.
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Jack P. Friedman
Signature

Jack P. Friedman
Reg. No. 44,688
Schmeiser, Olsen & Watts
3 Lear Jet Lane, Suite 201
Latham, NY 12110
(518) 220-1850

Dated:

10/1/02

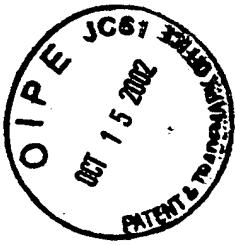
I certify that this document and fee is being deposited on 10/1/02 with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

Kim Dwileski
Signature of Person Mailing Correspondence

Kim Dwileski

Typed or Printed Name of Person Mailing Correspondence

CC:



H.W.
6/Reg for
Recs.
10-22-02

Docket No. EN9-98-072U82

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Enroth *et al.*

Group Art Unit: 3729

Filed: 2/6/01

Examiner: Smith, Sean Prentiss

Serial No.: 09/777,976

Title: WAVE SOLDER APPLICATION FOR BALL GRID ARRAY MODULES

Commissioner for Patents
Washington D.C. 20231

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Sir:

TECHNOLOGY CENTER R3700

This paper is being filed in response to the Office Action mailed July 3, 2002. Applicant's respectfully request that the above-identified application be reconsidered in view of the Amendments and Remarks that follow, that each of the presently pending claims be allowed, and that the application be passed to issue.

AMENDMENT

In The Claims

Currently pending claims 1-16 are as follows.

1. A method for constructing a printed circuit board assembly, comprising the steps of:

(a) providing a printed circuit board comprising:

a top surface comprising a top pad, wherein the top pad is electrically connectable to a top component;